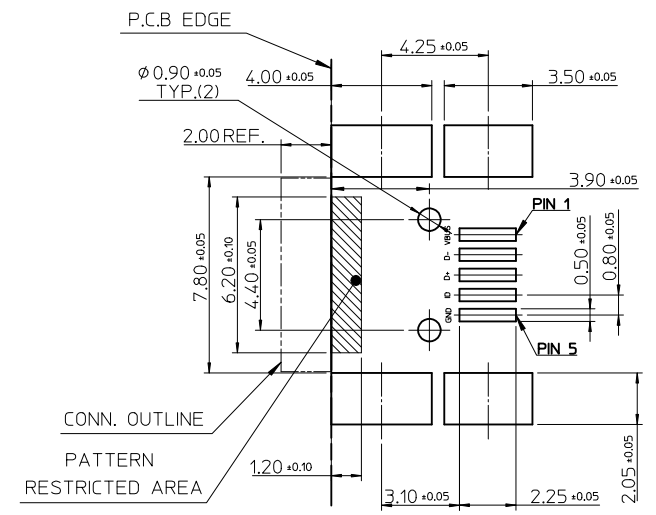


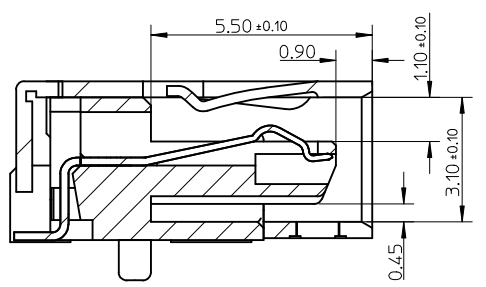
PRODUCT NO.	REMARK
67503-1020	N/A
67503-1120	HALOGEN FREE

NOTE :

- MATERIAL :
 - HOUSING : HIGH TEMPERATURE THERMAL PLASTIC , BLACK,UL94V-0
 - TERMINAL : COPPER ALLOY THICKNESS = 0.2 MM
 - SHIELD CASE : COPPER ALLOY THICKNESS = 0.4 MM
- PLATING :
 - TERMINAL:
 - CONTACT AREA : GOLD 0.75 MICROMETER MINIMUM.
 - SOLDER TAIL AREA : PURE TIN 1-3 MICROMETER PLATING.
 - SHIELD CASE :
 - PURE TIN 1-3 MICROMETER PLATING.
 - UNDER PLATING : NICKEL 1.0 MICROMETER MINIMUM.
- TAIL & NAIL COPLANARITY 0.1 mm MAXIMUM.
- PRODUCT SPECIFICATION REFER TO PS-67803-001.
- PACKAGING INFORMATION REFER TO PK-67503-001.
- COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV DIRECTIVE 2000/53/EC.



RECOMMENDED P.C.B. PATTERN LAYOUT



REMOVE PART NUMBER EC NO: SH2012-0143 DRWN:XQZHANG 2011/11/16 CHKD:GLLI 2011/11/16 APPR:XJSONG 2011/11/21	DESCRIPTION QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 8:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± ---	mm INCH ± --- ± --- ± 0.25 ± --- ± 0.25 ± ---	DRAWN BY LXWANG	DATE 2004/11/29	TITLE USB SERIES MINI-B REC. ASS'Y SMT TYPE (LEAD FREE)	MOLEX INCORPORATED		
		ANGULAR ± 3 °		CHECKED BY HARVEY	DATE 2004/11/29	APPROVED BY YTYAP	DATE 2004/11/29	DOCUMENT NO. SD-67503-010	SHEET NO. 1 OF 1
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				